

# HSF

NOTES:  
 Current Rating: 1.0AMP  
 Contact Resistance: 20mΩ Max  
 Withstand Voltage: 500V AC/DC  
 Insulation Resistance: 1000MΩ Min  
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze  
 Contact plating: Au Or Sn over Ni  
 Insulator Material: PA9T+30%GF UL94V-0

## Ordering Information

2344-2 XX M XX CUN X 3

No. of Pins per Row: 02~50Pin

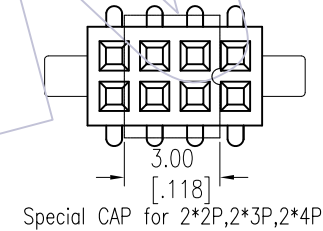
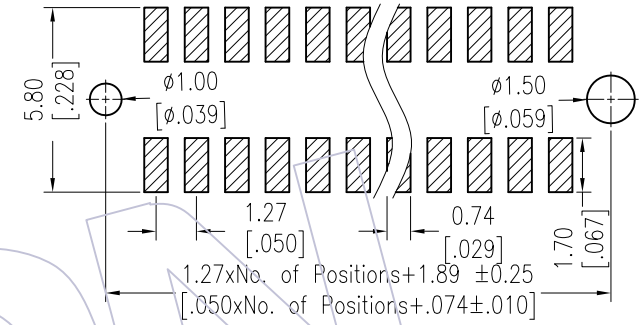
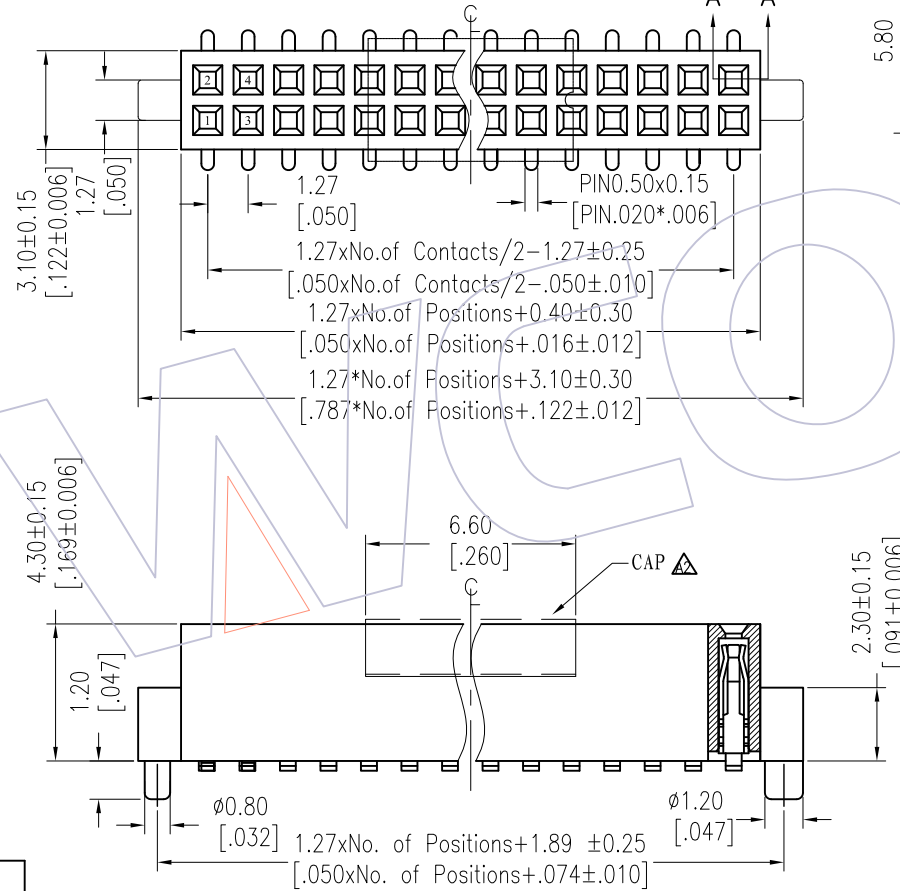
Contact Plating:

G0=Gold Flash  
 G3=10μ"Gold  
 G4=15μ"Gold  
 G5=30μ"Gold  
 S0=Gold Flash/Tin  
 S3=10μ"Gold/Tin  
 S4=15μ"Gold/Tin  
 S5=30μ"Gold/Tin  
 SN=Tin

Packing:

T=Tube  
 P=Tube+CAP  
 R=Tape&Reel+CAP

Recommended P.C.B Layout(Top Side)  
 (PCB BOARD TOLERANCE±0.05)



### SECTION A-A

Item	Pitch	Mating
Standard	1.27	310/1315/1320/3131/3133/3100
Alternate		

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
A2	2014/12/30	Modify CAP	-----	x.X ±0.40	Wang	2014/12/30	UNIT	mm	2344-2XXMXXCUNX3
A1	2013/08/21	Modify cap 2.00 → 1.80	-----	x.XX ±0.25	CHECK	DATE	SIZE	A4	TITLE: FH1.27mm DUAL SMT WITH DIFFERENT POST H=4.30
A0	2012/07/09	NEW	-----	x.XXX ±0.15	APPROVE	DATE	SHEET	1/1	Customer NO.
				Angle ± 3'			PROJ.		
				DIM TOL					